

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

IN THE CLAIMS

Please amend claims 25-30 as set forth below.

Claims 1-24 (Canceled)

25. (Currently Amended) A ~~manufacturing~~ method of manufacturing a resin-sealing type semiconductor device, comprising the steps of:

preparing a multi-link lead frame formed by linking ~~in a line with a~~ plurality of package areas in a line, each of the package areas including a plurality of inner leads and, a thin sheet-shaped insulating member joined to an end portion of each of said inner leads and capable of supporting a semiconductor chip;

thereafter mounting a said semiconductor chip on said insulating member in each of said package areas on which said inner leads and said insulating member are joined;

connecting surface electrodes of said semiconductor chips and said inner leads corresponding thereto by respective ~~a-wires~~;

forming a seal portion by resin-sealing said semiconductor chips, said wires, and said insulating members; and

separating a plurality of outer leads exposed from said seal portion, from a frame section of said lead frame.

26. (Currently Amended) A ~~manufacturing~~ method of manufacturing a resin-sealing type semiconductor device, comprising the steps of:

preparing a matrix frame ~~formed~~ by arranging a plurality of package areas in a matrix arrangement, each of the package areas including a plurality of inner leads and, a thin sheet-shaped insulating member joined to an end portion of each of said inner leads and capable of supporting a semiconductor chip;

thereafter mounting a said semiconductor chip on said insulating member in each of said package areas on which said inner leads and said insulating member are joined;

connecting surface electrodes of said semiconductor chips and said inner leads corresponding thereto by respective a-wires;

forming a seal portion by resin-sealing said semiconductor chips, said wires, and said insulating members; and

separating a plurality of outer leads exposed from said seal portion, from a frame section of said matrix frame.

27. (Currently Amended) The ~~manufacturing~~ method of manufacturing a semiconductor device according to claim 25, ~~further comprising a~~ wherein said mounting is performed by

step ~~of mounting~~ said semiconductor chip on a surface of an inner lead arrangement side of said insulating member ~~when said semiconductor chip is mounted on said insulating member.~~

28. (Currently Amended) The ~~manufacturing~~ method of manufacturing a semiconductor device according to claim 25, wherein said mounting step is performed ~~semiconductor chip is arranged and mounted~~ such that a length of a shorter side of a main surface of said semiconductor chip formed in a ~~an~~ quadrilateral shape is twice or less than twice a distance from a tip of the inner leads arranged at the farthest location from a center line of the semiconductor chip in a plane direction, to said semiconductor chip, ~~when said semiconductor chip is mounted on said insulating member.~~

29. (Currently Amended) The ~~manufacturing~~ method of manufacturing a semiconductor device according to claim 25, ~~further comprising~~ wherein said preparing step includes a step of being assembled by using said lead frame in which said inner leads and said insulating member are joined by providing an adhesive layer disposed throughout the entirety of a surface of an inner lead arrangement side of said insulating member.

30. (Currently Amended) The ~~manufacturing~~ method of manufacturing a semiconductor device according to claim 25, ~~further comprising~~ wherein said preparing step includes a step of ~~being assembled by using said lead frame in which said inner leads and said insulating member are joined by~~ providing an adhesive layer disposed only on a lead joining portion of a surface of an inner lead arrangement side of said insulating member.